

L Number	Hits	Search Text	DB	Time stamp
20	8298	(sloped or angles or slant) with (via or th or (through adj hole))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 17:20
21	6	((sloped or angles or slant) with (via or th or (through adj hole))) and interposer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 17:17
22	787	(slant with (via or th or (through adj hole)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 17:20
23	1	((slant with (via or th or (through adj hole)))) and interposer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 17:22
25	23	(257/\$.ccls. and ((shape or slant or angle) with ((through adj hole) or via or "th"))) and interposer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 17:25
24	941	257/\$.ccls. and ((shape or slant or angle) with ((through adj hole) or via or "th"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 17:40
26	0	20020030245.URPN.	USPAT	2002/08/09 17:33
27	0	20020030245.URPN.	USPAT	2002/08/09 17:33
28	1	("5585675").PN.	USPAT	2002/08/09 18:02
29	12	5585675.URPN.	USPAT	2002/08/09 17:45
30	4	("4525921" "4734825" "4862249" "5434452").PN.	USPAT	2002/08/09 17:47
31	10	4051563.URPN.	USPAT	2002/08/09 17:57
32	243	(interposer or pcb or pwb) and chip and (circuit adj card)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 18:18
33	25	((interposer or pcb or pwb) and chip and (circuit adj card)) and (pth or (plated near (hole or via)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 18:19
35	10	(interposer and chip and (circuit adj card)) and (pth or (plated near (hole or via)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 18:23
36	2	((("5634268") or ("5796591"))).PN.	USPAT	2002/08/09 18:23
34	85	interposer and chip and (circuit adj card)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 18:44
37	25	5574630.URPN.	USPAT	2002/08/09 18:37
38	0	interposer.tti. and (pth or (plated near hole))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 18:45
39	1	interposer.ti. and (pth or (plated near hole))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 18:47

interposer and (pth or (plated near hole)).ti.

	0	(pth or (plated near hole)).ti. and interposer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT USPAT USPAT USPAT	2002/08/09 18:47 2002/08/09 18:48 2002/08/09 18:54 2002/08/09 18:53 2002/08/09 18:54 2002/08/09 18:54
43	1	("6191487").PN.		
44	1	6191487.URPN.		
45	1	6191487.URPN.		
	8	("4912545" "5394303" "5406701" "5432729" "5569880" "5657206" "5737191" "5869886").PN.		
46	1	("5585675").PN.		
47	72	(sloped or slope or slant or slanted or angular or angle or diagonal) with (pth or (plated near hole))	USPAT USPAT	2002/08/09 18:57 2002/08/09 19:55
48	44145	(sloped or slope or slant or slanted or angular or angle or diagonal) with (via or pth or (plated adj through hole))	USPAT	2002/08/09 19:56
49	18958	"v" with (via or pth or (plated adj through hole))	USPAT	2002/08/09 19:58
50	1094	("v" adj shape) same (via or pth or (plated adj through hole))	USPAT	2002/08/09 19:59
51	341	("v" adj shape) with (via or pth or (plated adj through hole))	USPAT	2002/08/09 20:21
52	530585	shape with through hole	USPAT	2002/08/09 20:06
53	462020	shape near through hole	USPAT USPAT USPAT	2002/08/09 20:07 2002/08/09 20:08 2002/08/09 20:08
54	3632	(shape near through hole) and (pth or (plated adj through))	USPAT	2002/08/09 20:26
55	109	((shape near through hole) and (pth or (plated adj through))) and (interposer)	USPAT	2002/08/09 21:05
56	80	(via or pth or (plated adj through hole)) and ((offset or (off adj set)) near pad)	USPAT	2002/08/09 20:30
57	213	interposer and stress and hole	USPAT	2002/08/09 20:32
58	0	(porous with interposer) and stress	USPAT	2002/08/09 20:34
59	9	(porous with interposer)	USPAT	2002/08/09 20:34
60	9	porous with interposer	USPAT	2002/08/09 21:03
61	0	pore with interposer	USPAT	2002/08/09 20:55
62	15	porous same interposer	USPAT	2002/08/09 21:03
63	15	5531022.URPN.	USPAT	2002/08/09 21:05
64	0	swiss same interposer	USPAT	2002/08/09 21:06
65	3	interposer and (stress with hole)	USPAT	2002/08/09 21:19
66	108	(interposer and stress and hole) and tape	USPAT	2002/08/09 21:21
67	25	((interposer and stress and hole) and tape) and moisture	USPAT	2002/08/09 21:22
68	593	substrate and (stress with hole)	USPAT	2002/08/09 21:22
69	4	(porous adj substrate) and ((plated adj through adj hole) or pth) and stress	USPAT	2002/08/09 21:24
70	0	(porous adj (compliant or elastomer or elastomeric)) and ((plated adj through adj hole) or pth) and stress	USPAT	2002/08/09 21:23
71	0	(porous adj (compliant or elastomer or elastomeric)) and ((plated adj through adj hole) or pth)	USPAT	2002/08/09 21:25
72	258	(porous adj (compliant or elastomer or elastomeric))) and (pth or (plated adj through))	USPAT	2002/08/09 21:25
73	0	((porous adj (compliant or elastomer or elastomeric))) and (pth or (through adj hole))	USPAT	2002/08/09 21:25
74	18	((porous adj (compliant or elastomer or elastomeric))) and (pth or (through adj hole))	USPAT	2002/08/09 21:25
75	1	(porous with interposer) and (pth or (through adj hole))	USPAT	2002/08/09 21:25
	9	porous with interposer	USPAT	2002/08/09 21:25